Information Disclosure Statement By Applicant (Use Several Sheets if Necessary)	Applicant: WALLACE Filing Date 01/04/2002	Group 2811

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A1						

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	B1							

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
qv	C1	John Barber, "Plastic Packaging and the Effects of Surface Mount Soldering Techniques," Microchip Technology, Inc., 12 pages, 1995
qv	C2	Lai et al., Nordic Electronic Packaging Guideline, Chapter A, printed from: http://www.extra.ivf.se/mgl/A-WireBonding/ChapterA.htm, on March 16, 2004, 25 Pages
qv	C3	Prof. Daniel F. Baldwin, "Fundamentals of IC Assembly," McGraw-Hill, Chapter. 9, pages 342-353, 2001
qv	C4	Semiconductor Packaging Assembly Technology, printed from www.national.com, 8 pages, 1999

Examiner	Date Considered
[signature]	04/02/04

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.